

ULTRA-LOW JITTER DUAL 2 × 2 CROSSPOINT SWITCH w/ CML OUTPUTS AND INTERNAL I/O TERMINATION

Precision Edge™ SY58024U

FEATURES

- Guaranteed AC performance over temperature and voltage:
 - >10.7Gbps data throughput
 - <60ps t_r/t_f times
 - <350ps t_{pd} (IN-to-Q)
 - <20ps skew
- Low jitter:
 - <10ps_{pp} total jitter (clock)
 - <1ps_{rms} random jitter (data)
 - <10ps_{pp} deterministic jitter (data)
- Crosstalk induced jitter: <0.7ps_{rms}
- Unique, patent-pending input isolation minimizes adjacent channel crosstalk
- Accepts an input signal as low as 100mV
- Unique, patent-pending input termination and VT pin accepts DC-coupled and AC-coupled differential inputs: LVPECL, LVDS, and CML
- **■** Fully differential inputs/outputs
- 50 Ω source terminated CML outputs
- Power supply 2.5V \pm 5% and 3.3V \pm 10%
- Industrial -40°C to +85°C temperature range
- Available in 32-pin (5mm × 5mm) MLFTM package

APPLICATIONS

- Gigabit Ethernet data/clock routing
- SONET data/clocking routing
- Switch fabric clock routing
- Redundant switchover
- Backplane redundancy



Precision Edge™

DESCRIPTION

The SY58024U is a 2.5V/3.3V precision, high-speed, fully differential dual CML crosspoint switch. The SY58024U is optimized to provide two identical output copies with less than 20ps of skew and ultra-low jitter. The SY58024U can process clock signals as fast as 6GHz or data patterns up to 10.7Gbps.

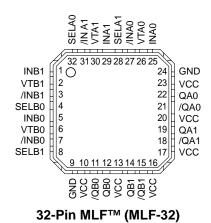
The differential input includes Micrel's unique, 3-pin input termination architecture that allows the SY58024U to directly interface to LVPECL, LVDS, and CML differential signal (AC- or DC-coupled) without any level-shifting or termination resistor networks in the signal path. The CML outputs features a 400mV typical swing into 50Ω loads, and provides an extremely fast rise/fall time guaranteed to be less than 60ps.

The SY58024U operates from a 2.5V $\pm 5\%$ supply or 3.3V $\pm 10\%$ supply and is guaranteed over the full industrial temperature range (–40°C to +85°C). For applications that require high-speed single channel CML switches, consider the SY58023U. The SY58024U is part of Micrel's high-speed, Precision EdgeTM product line.

Data sheets and support documentation can be found on Micrel's website at www.micrel.com.

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PACKAGE/ORDERING INFORMATION



Ordering Information⁽¹⁾

Part Number	Package Type	Operating Range	Package Marking	Lead Finish
SY58024UMI	MLF-32	Industrial	SY58024U	Sn-Pb
SY58024UMITR ⁽²⁾	MLF-32	Industrial	SY58024U	Sn-Pb
SY58024UMY	MLF-32	Industrial	SY58024U with "Y" designator	Pb-Free
SY58024UMYTR ⁽²⁾	MLF-32	Industrial	SY58024U with "Y" designator	Pb-Free

Notes:

- 1. Contact factory for die availability. Dice are guaranteed at $T_{\rm A}$ = 25°C, DC electricals only.
- 2. Tape and Reel.

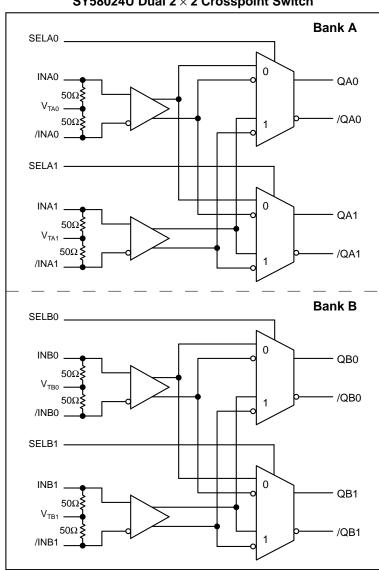
PIN DESCRIPTION

Pin Number	Pin Name	Pin Function
25, 27 29, 31, 1, 3, 5, 7	INA0, /INA0, INA1, /INA1, INB1, /INB1 INB0, /INB0	Differential Signal: Each pin of this pair internally terminates with 50Ω to the VT pin. The input will default to an indeterminate state if left open. See "Input Interface Application" section.
26, 30 2, 6	VTA0, VTA1, VTB1, VTB0	Input Termination Center-Tap: Each input terminates to this pin. The VT pin provides a center-tap for each input (IN, /IN) to a termination network for maximum interface flexibility. See "Input Interface Application" section.
32, 28, 8, 4	SELA0, SELA1, SELB1, SELB0	Select Input: TTL/CMOS select input controls that selects inputs IN0, or IN1, for their respective banks A and B. Each input is internally connected to a $25k\Omega$ pull-up resistor and will default to a logic high state if left open.
9,24	GND, Exposed Pad	Ground. Exposed pad must be connected to a ground plane that is the same potential as the device ground pins.
10,13,16, 17, 20, 23	VCC	Positive Power Supply: Bypass with $0.1\mu F \mid 0.01\mu F$ low ESR capacitors as close to the V_{CC} pins as possible.
11, 12, 14, 15 18, 19, 21, 22	/QB0, QB0, QB1, /QB1, /QA1, QA1, /QA0, QA0	CML Differential Output Pairs: Differential buffered output copy of the selected input signal. The CML single-ended output swing is typically 400mV into 50Ω or 100Ω across the pair. Unused output pairs may be left floating with no impact on jitter. See "CML Output Termination" section.

TRUTH TABLE

SELA0	SELA1	QA0	QA1	SELB0	SELB1	QB0	QB1
0	0	INA0	INA0	0	0	INB0	INB0
0	1	INA0	INA1	0	1	INB1	INB1
1	0	INA1	INA0	1	0	INB1	INB0
1	1	INA1	INA1	1	1	INB1	INB1

FUNCTIONAL BLOCK DIAGRAM



SY58024U Dual 2×2 Crosspoint Switch

Absolute Maximum Ratings⁽¹⁾

Supply Voltage (V _{CC})	0.5V to +4.0V
Input Voltage (V _{IN})	0.5V to V _{CC}
CML Output Voltage (V _{OUT}) V _{CC}	$-1.0V$ to V_{CC} +0.5V
Current (V _T)	
Source or Sink Current on VT pin	±100mA
Input Current (V _T)	
Source or Sink Current on IN, /IN.	±50mA
Lead Temperature (soldering, 20 sec.)	260°C
Storage Temperature (T _S)	65°C +150°C

Operating Ratings⁽²⁾

Supply Voltage (V _{CC})	+2.375V to +3.60V
Ambient Temperature (T _A)	–40°C to +85°C
Package Thermal Resistance ⁽³⁾	
$MLF^{\mathsf{TM}}\left(\theta_{JA}\right)$	
Still-Air	35°C/W
500lfpm	28°C/W
MLF™ (ψ _{JB})	
Junction-to-board resistance	20°C/W

DC ELECTRICAL CHARACTERISTICS(4)

 $T_{\Delta} = -40^{\circ}\text{C} \text{ to } +85^{\circ}\text{C}.$

Symbol	Parameter	Condition	Min	Тур	Max	Units
V _{CC}	Power Supply Voltage	2.5V nominal 3.3V nominal	2.375 3.0	2.5 3.3	2.625 3.60	V V
I _{CC}	Power Supply Current	V_{CC} = max., current through internal 50 Ω source termination resistor included.		200	250	mA
$\overline{V_{IH}}$	Input HIGH Voltage	IN, /IN; Note 5	V _{CC} -1.6		V _{cc}	V
V_{IL}	Input LOW Voltage	IN, /IN	0		V _{IH} −0.1	V
$\overline{V_{IN}}$	Input Voltage Swing	IN, /IN, see Figure 1a.	0.1		1.7	V
V _{DIFF_IN}	Differential Input Swing	IN, /IN, see Figure 1b.	0.2			V
R _{IN}	IN-to-V _T Resistance		40	50	60	Ω
IN to V _T					1.28	V

CML OUTPUT DC ELECTRICAL CHARACTERISTICS(4)

 V_{CC} = +3.3V ±10% or +2.5V ±5%; R_L = 100 Ω across each pair; T_A = -40°C to +85°C, unless otherwise stated.

Symbol	Parameter	Condition	Min	Тур	Max	Units
V _{OH}	Output HIGH Voltage	Q0, /Q0; Q1, /Q1	V _{CC} -0.020		V _{CC}	V
V _{OUT}	Output Voltage Swing	Q0, /Q0; Q1, /Q1; see Figure 1a.	325	400	500	mV
V _{DIFF_OUT}	Differential Voltage Swing	Q0, /Q0; Q1, /Q1; see Figure 1b.	650	800	1000	mV
R _{OUT}	Output Source Impedance	Q0, /Q0; Q1, /Q1	40	50	60	Ω

Notes:

- 1. Permanent device damage may occur if "Absolute Maximum Ratings are exceeded." This is a stress rating only and functional operation is not implied at conditions other than those detailed in the operational sections of this data sheet. Exposure to "Absolute Maximum Rating" conditions for extended periods may affect device reliability.
- 2. The data sheet limits are not guaranteed if the device is operated beyond the operating ratings.
- 3. Thermal performance assumes exposed pad is soldered (or equivalent) to the device's most negative potential (GND) on the PCB. θ_{JA} and ψ_{JB} are characterized for 4-layer boards in still air, unless otherwise stated.
- 4. The circuit is designed to meet the DC specifications shown in the above table after thermal equilibrium has been established.
- 5. V_{IH} (min.) not lower than 1.2V.

AC ELECTRICAL CHARACTERISTICS(6)

 V_{CC} = +2.5V ±5% or +3.3V ±10%; R_L = 100 Ω across each output pair; T_A = -40°C to +85°C, unless otherwise stated.

Symbol	Paramete	r	Condition		Min	Тур	Max	Units
f _{MAX}	Maximum	Operating Frequency	$V_{IN} \ge 100 \text{mV}; V_{OUT} \ge 200 \text{mV}$	Clock	6			GHz
				NRZ Data	10.7			Gbps
t _{pd}	Propagation	on Delay	IN-to-Q		200		350	ps
			SEL-to-Q		100		400	ps
t _{SKEW}	Channel-to (Within Ba	o-Channel Skew ank)	Note 7				20	ps
	Part-to-Pa	art Skew	Note 8				75	ps
t _{JITTER}	Clock	Cycle-to-Cycle Jitter	Note 9				1	psrms
		Total Jitter	Note 10				10	ps _{pp}
	Data	Random Jitter	Note 11				1	psrms
		Deterministic Jitter	Note 12				10	ps _{pp}
		Crosstalk Induced Jitter Adjacent Channel	Note 13				0.7	psrms
t _r , t _f	Output Ris	se/Fall Time	20% to 80% at full swing.		25		60	ps

Notes:

- 6. High frequency AC-parameters are guaranteed by design and characterization.
- 7. Skew is measured between outputs of the same bank under identical transitions.
- 8. Skew is defined for two parts with identical power supply voltages at the same temperature and with no skew of the edges at the respective inputs.
- 9. Cycle-to-cycle jitter definition: The variation of periods between adjacent cycles, $T_n T_{n-1}$ where T is the time between rising edges of the output signal.
- 10. Total jitter definition: With an ideal clock input of frequency ≤ f_{MAX}, no more than one output edge in 10¹² output edges will deviate by more than the specified peak-to-peak jitter value.
- 11. Random jitter is measured with a K28.7 comma detect character pattern, measured at 2.5Gbps-3.2Gbps.
- 11. Deterministic jitter is measured at 2.5Gbps–3.2Gbps with both K28.5 and 2^{23} –1 PRBS pattern.
- 13. Crosstalk induced jitter is defined as the added jitter that results from signals applied to two adjacent channels. It is measured at the output while applying similar, differential clock frequencies that are asynchronous with respect to each other at inputs.

SINGLE-ENDED AND DIFFERENTIAL SWINGS

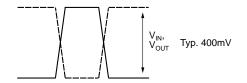


Figure 1a. Single-Ended Voltage Swing

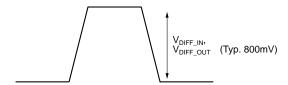


Figure 1b. Differential Voltage Swing

TIMING DIAGRAM

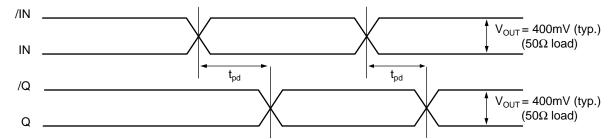


Figure 2a. AC Timing Diagram IN-to-Q

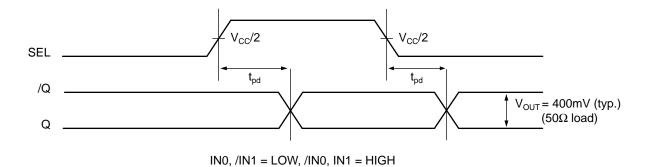
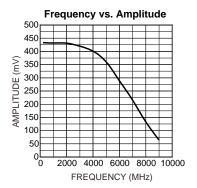
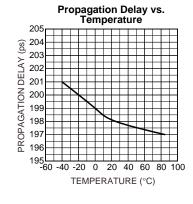


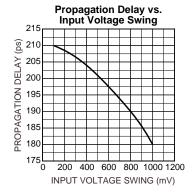
Figure 2b. AC Timing Diagram SEL-to-Q

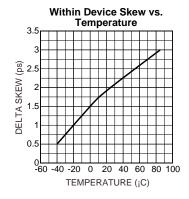
TYPICAL OPERATING CHARACTERISTICS

 V_{CC} = 2.5V, V_{IN} = 100mV, T_A = 25°C, unless otherwise noted.



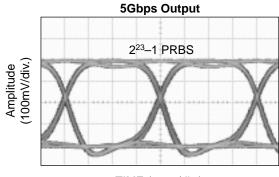




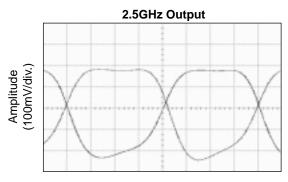


FUNCTIONAL CHARACTERISTICS

 V_{CC} = 2.5V, V_{IN} = 100mV, T_A = 25°C, unless otherwise noted.

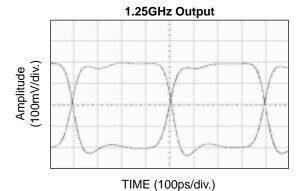


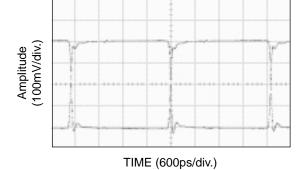
TIME (50ps/div.)



TIME (50ps/div.)

200MHz Output





INPUT STAGE

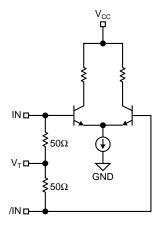


Figure 3. Simplified Differential Input Buffer

INPUT INTERFACE APPLICATIONS

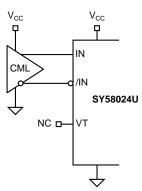


Figure 4a. DC-Coupled CML Input Interface

Option: may connect V_T to V_{CC}

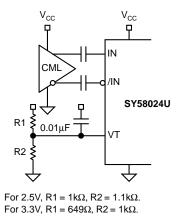


Figure 4b. AC-Coupled CML Input Interface

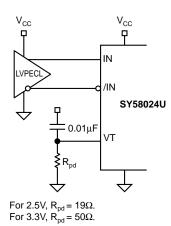
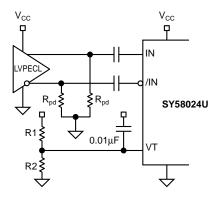


Figure 4c. DC-Coupled LVPECL Input Interface



For 2.5V, R_{pd} = $50\Omega,\,R1$ = $1k\Omega,\,R2$ = $1.1k\Omega.$ For 3.3V, R_{pd} = $100\Omega,\,R1$ = $649\Omega,\,R2$ = $1k\Omega.$

Figure 4d. AC-Coupled LVPECL Input Interface

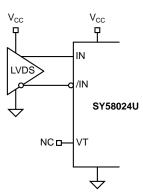


Figure 4e. LVDS Input Interface

CML OUTPUT TERMINATION

Figures 5 and Figure 6 illustrates how to terminate a CML output using both the AC-coupled and DC-coupled

configuration. All outputs of the SY58024U are 50Ω with a 16mA current source.

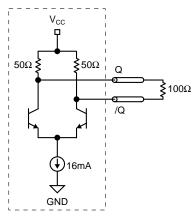


Figure 5. CML DC-Coupled Termination

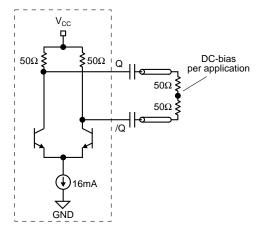
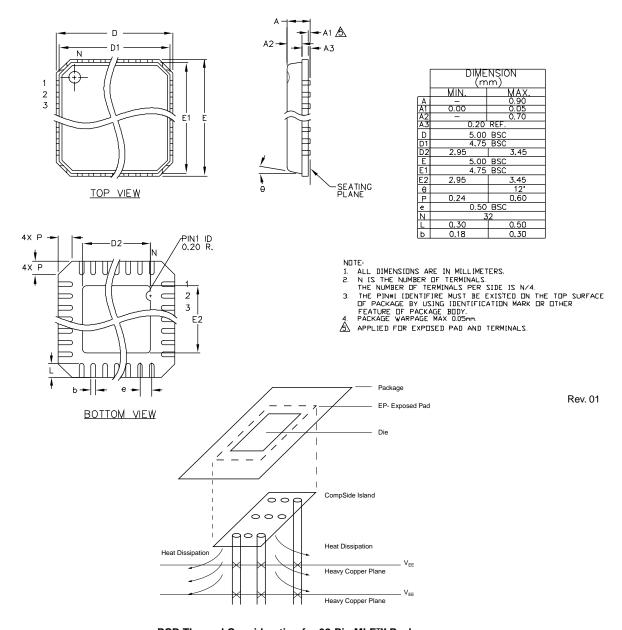


Figure 6. CML AC-Coupled Termination

RELATED PRODUCT AND SUPPORT DOCUMENTATION

Part Number	Function	Data Sheet Link
SY58023U	Ultra-low Jitter 2x2 Crosspoint Switch w/CML Outputs and Internal I/O Termination	http://www.micrel.com/product-info/products/SY58023U.shtml
SY58024U	Ultra-low Jitter Dual 2x2 Crosspoint Switch w/CML Outputs and Internal I/O Termination	http://www.micrel.com/product-info/products/sy58024u.shtml
	32-MLF Manufactering Guidelines Exposed Pad Application Note	www.amkor.com/products/notes_papers/MLF_AppNote.pdf
	HBW Solutions	http://www.micrel.com/product-info/as/solutions.shtml

32 LEAD *Micro*LeadFrame™ (MLF-32)



PCB Thermal Consideration for 32-Pin MLF™ Package (Always solder, or equivalent, the exposed pad to the PCB)

Package Notes:

- 1. Package meets Level 2 qualification.
- 2. All parts are dry-packaged before shipment.
- 3. Exposed pads must be soldered to a ground for proper thermal management.

MICREL, INC. 1849 FORTUNE DRIVE SAN JOSE, CA 95131 USA

TEL + 1 (408) 944-0800 FAX + 1 (408) 474-1000 WEB http://www.micrel.com

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